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Form PTO-1449 (REV. 8-83)		US Dept. of Commerce PATENT & TRADEMARK OFFICE		ATTY DOCKET NO. 103092.02		NEW RULE 1.53(b) CONTINUATION OF APPLICATION NO. 09/589,353	
INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary)				APPLICANT(S) Nobuaki HASHIMOTO		GROUP 2823	
				FILING DATE November 26, 2001			

U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	
<i>Lee</i>		5,019,944	05/1991	ISHI et al.	361	783	
		5,286,417	02/1994	MAHMOUD et al.	252	518	
		5,431,571	07/1995	HANRAHAN et al.	439	91	
		5,506,514	04/1996	DIFRANCESCO	324	757	
		5,624,268	04/1997	MAEDA et al.	439	66	
		5,766,982	06/1998	AKRAM et al.	438	51	
		5,628,919	05/13/97	TOMURA et al.	216	18	
		5,805,425	08/1998	PETERSON	361	769	
		5,936,848	08/1999	MEHR et al.	361	777	
		6,011,312	01/2000	NAKAZAWA et al.	257	778	
	<i>Lee</i>		6,011,694	01/04/00	HIRAKAWA	361	774

FOREIGN PATENT DOCUMENTS						
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS
<i>Lee</i>		9-51018	02/1997	Japan		
		9-199632	07/1997	Japan		
		9-266231	10/1997	Japan		
		9-298252	11/1997	Japan		
		A 62-52953 (English abstract only)	03/07/87	Japan		
<i>Lee</i>		EP 0 704 899 A2	04/03/96	Europe		

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)	
<i>Lee</i>	XP 000851211(10/13/97): SCHUELLER, R.D., "New Chip Scale Package with CTE Matching to the Board", 1997 IEEE/CPMT Int'l Electronics Manufacturing Technology Symposium, pp. 205-215.
<i>Lee</i>	XP 000624972(05/21/95): MATSUDA, Shuichi et al., "Simple-Structure, Generally Applicable Chip-Scale Package", 1995 IEEE, pp. 218-223.

EXAMINER <i>Kevin Meng Lee</i>	DATE CONSIDERED 12/9/02
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Examiner: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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